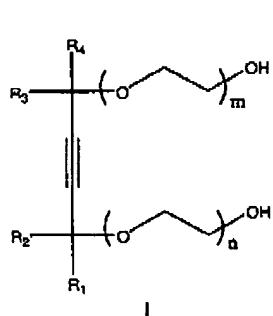


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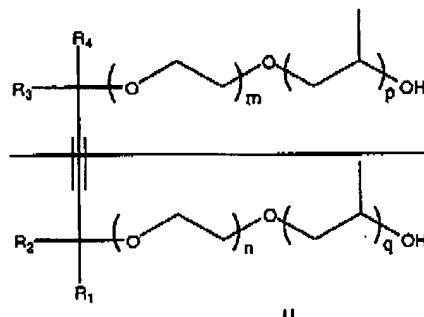
Amendments to the Specification

Please replace paragraph [0007] at page 3 of the specification with the following new paragraph [0007]:

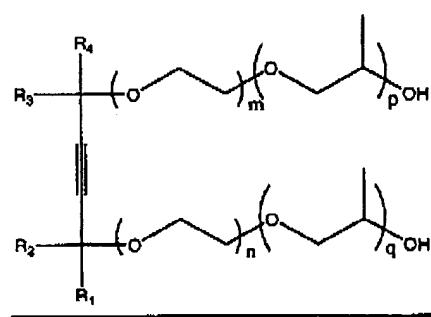
[0007] Process solutions for the removal of processing residue from semiconductor substrates following CMP processing and methods employing same are disclosed herein. Specifically, in one aspect of the present invention, there is provided a method for reducing defects in the manufacture of semiconductor devices comprising: providing a post-CMP processed substrate wherein at least a portion of the substrate comprises a low dielectric constant film and contacting the substrate with a process solution comprising about 10 ppm to about 500,000 ppm of at least one surfactant having the formula (I), (II), (III), (IVa), (IVb), (V), (VI), or (VII):



I

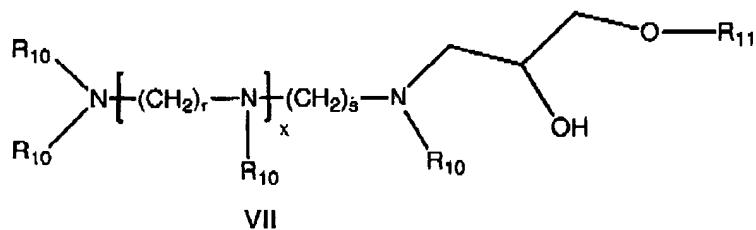
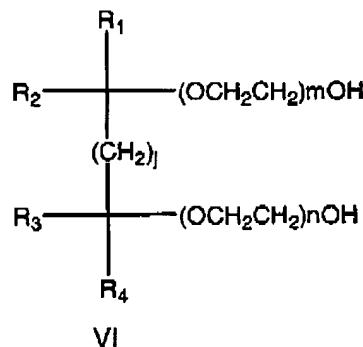
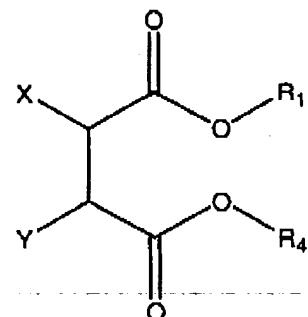
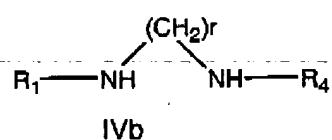
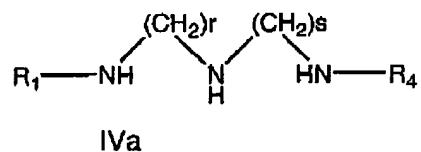
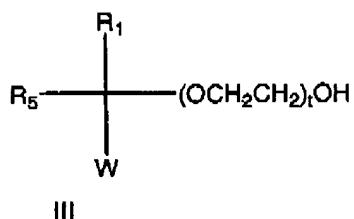


II



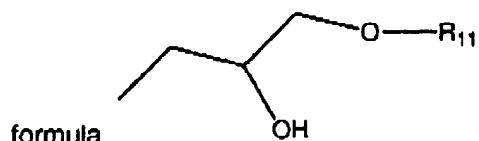
III

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wherein R_1 and R_4 are each independently a straight or a branched alkyl group having from 3 to 10 carbon atoms; R_2 and R_3 are each independently a hydrogen atom or an alkyl group having from 1 to 5 carbon atoms; R_5 is a straight or a branched alkyl group having from 1 to 10 carbon atoms; R_{10} is independently H or a group represented by the

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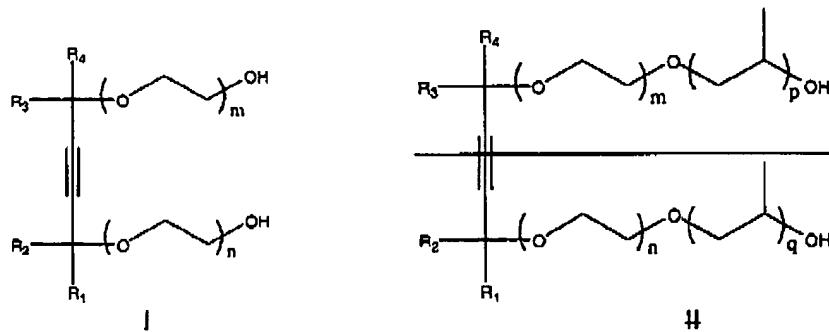


; R_{11} is a straight, branched, or cyclic alkyl group

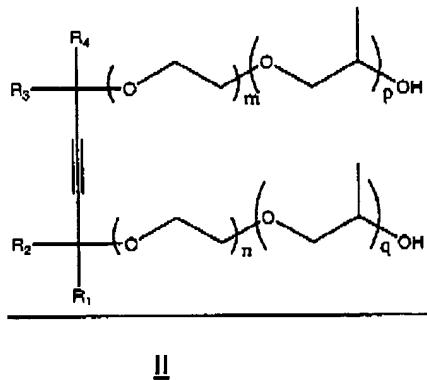
having from 4 to 22 carbon atoms; W is a hydrogen atom or an alkynyl group; X and Y are each independently a hydrogen atom or a hydroxyl group; m, n, p, and q are each independently a number that ranges from 0 to 20; r and s are each independently 2 or 3; t is a number that ranges from 0 to 2; j is a number that ranges from 1 to 5; and x is a number that ranges from 1 to 6.

Please replace paragraph [0017] at page 8 of the specification with the following new paragraph [0017]:

[0017] In certain embodiments of the present invention, the process solution may contain one or more nonionic surfactants that are acetylenic diol derivatives. The surfactants of the present invention may be represented by the following formula I or formula II:



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wherein R₁ and R₄ are each independently a straight or a branched alkyl chain having from 3 to 10 carbon atoms; R₂ and R₃ are each independently a hydrogen atom or an alkyl chain having from 1 to 5 carbon atoms; and m, n, p, and q are each independently a number that ranges from 0 to 20. The surfactants are commercially available from Air Products and Chemicals, Inc. of Allentown, PA, the assignee of the present invention, under the trade names SURFYNOL® and DYNOL®. In certain preferred embodiments, the acetylenic diol portion of the molecule of formulas I or II is 2,4,5,9-tetramethyl-5-decyne-4,7-diol or 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol. The acetylenic diol derived surfactants may be prepared in a number of ways including the methods described, for example, in U. S. Pat. No. 6,313,182 and EP 1115035A1, which are assigned to the assignee of the present invention and incorporated herein by reference in their entirety.